



Product Change Notification

CN-202203020F

Issue date: 06 Jul 2022

Effective date: 18 Oct 2022

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Change of back side metallization thickness - wave 2

Change Category

<input checked="" type="checkbox"/>	<input type="checkbox"/>				
Wafer	Assembl				
Fab	y				
Process	Process	<input type="checkbox"/>	Product Marking	<input type="checkbox"/>	Test Design
<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	Mechanical	<input type="checkbox"/>	Location
Wafer	Assembl		Specification	<input type="checkbox"/>	Test Errata
Fab	y	<input type="checkbox"/>		<input type="checkbox"/>	Process
Material	Materials		Packing/Shipping/Labelin	<input type="checkbox"/>	Test Electrical
s	<input type="checkbox"/>	g		<input type="checkbox"/>	Equipmen spec./Tes
<input type="checkbox"/>	Assembl			t	t coverage
Wafer	y				
Fab	Location				
Location					

Details of this change

The back side metallization thickness will be changed from 2.15 µm to 1.75 µm. The change of back side metallization thickness is combined with the introduction of 8 inch wafer diameter for product type PBSS5320D.

Current products: back side metallization thickness 2.15 µm; 8 inch (where affected) and 6 inch (where affected)

Changed products: back side metallization thickness 1.75 µm; 8 inch

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

SQR_202203020F.pdf: https://qcm.nexperia.com/Document/DOC-540593/SQR_202203020F.pdf

PCNForm_Rev_5_0_2.zip: https://qcm.nexperia.com/Document/DOC-540590/PCNForm_Rev_5_0_2.zip

Delta-Qualification-Matrix-ZVEI-5_0_14.zip:
https://qcm.nexperia.com/Document/DOC-540589/Delta-Qualification-Matrix-ZVEI-5_0_14.zip

Why do we implement this change?

- To increase efficiency of volume production.
- Capacity expansion in wafer fab
- Continued alignment with world technology trends on state of the art production tools for discrete components.

Identification of affected products

Changed product can be identified by date code after implementation.
8 inch products can be identified by a marker on the die surface.

Product availability

Production

Planned first shipment: 01 Nov 2022

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Disposition of old products

Supply using 6 inch wafer will be continued in parallel to 8 inch wafer production.

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 05 Aug 2022. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the

Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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